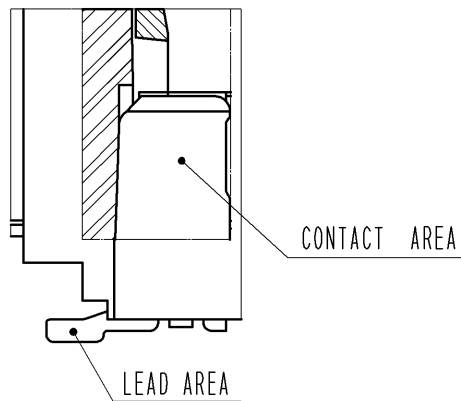
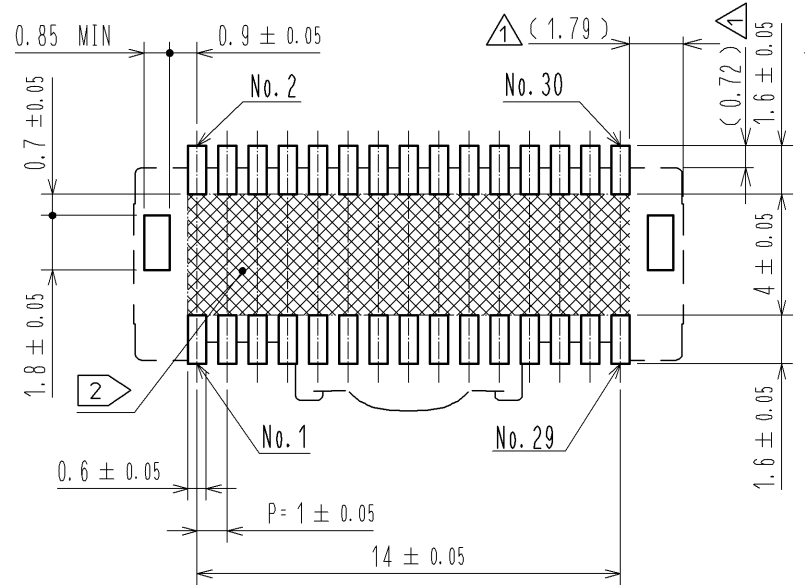


A (10:1)

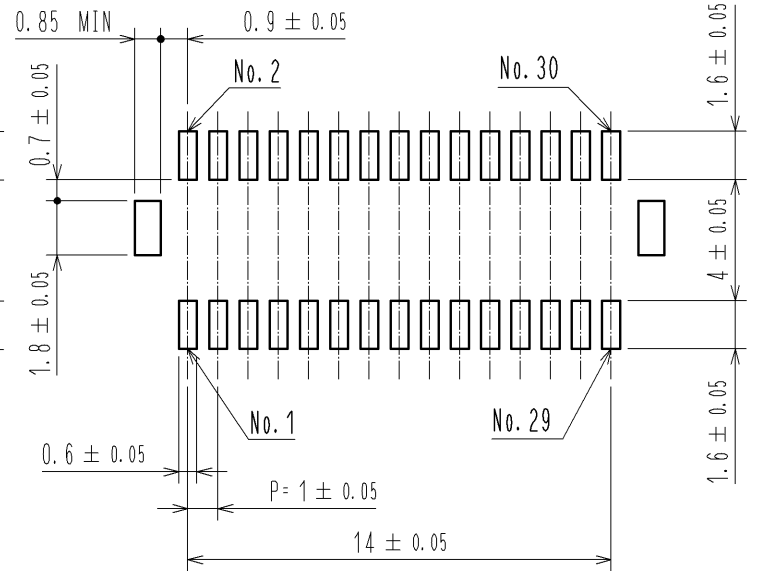


RECOMMENDED PCB LAYOUT (MOUNTING SURFACE SIDE) (FREE)

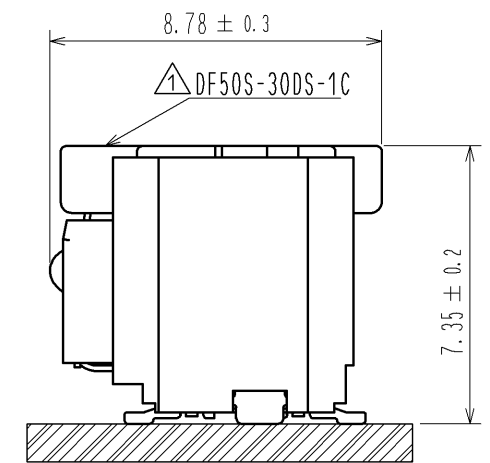
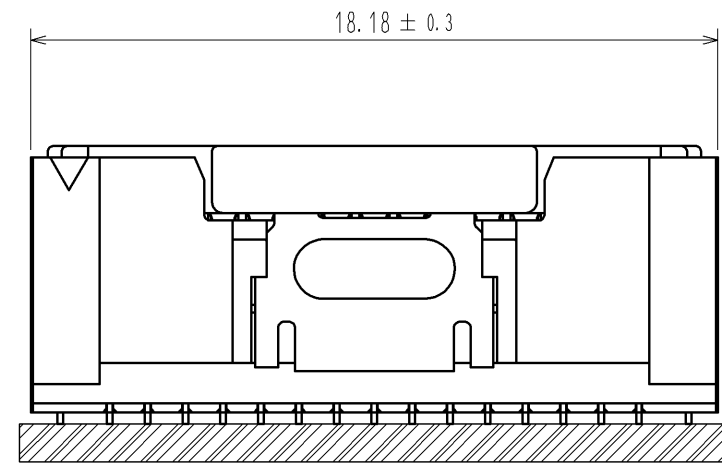


RECOMMENDED METAL MASK (FREE)

THICKNESS : 0.1mm



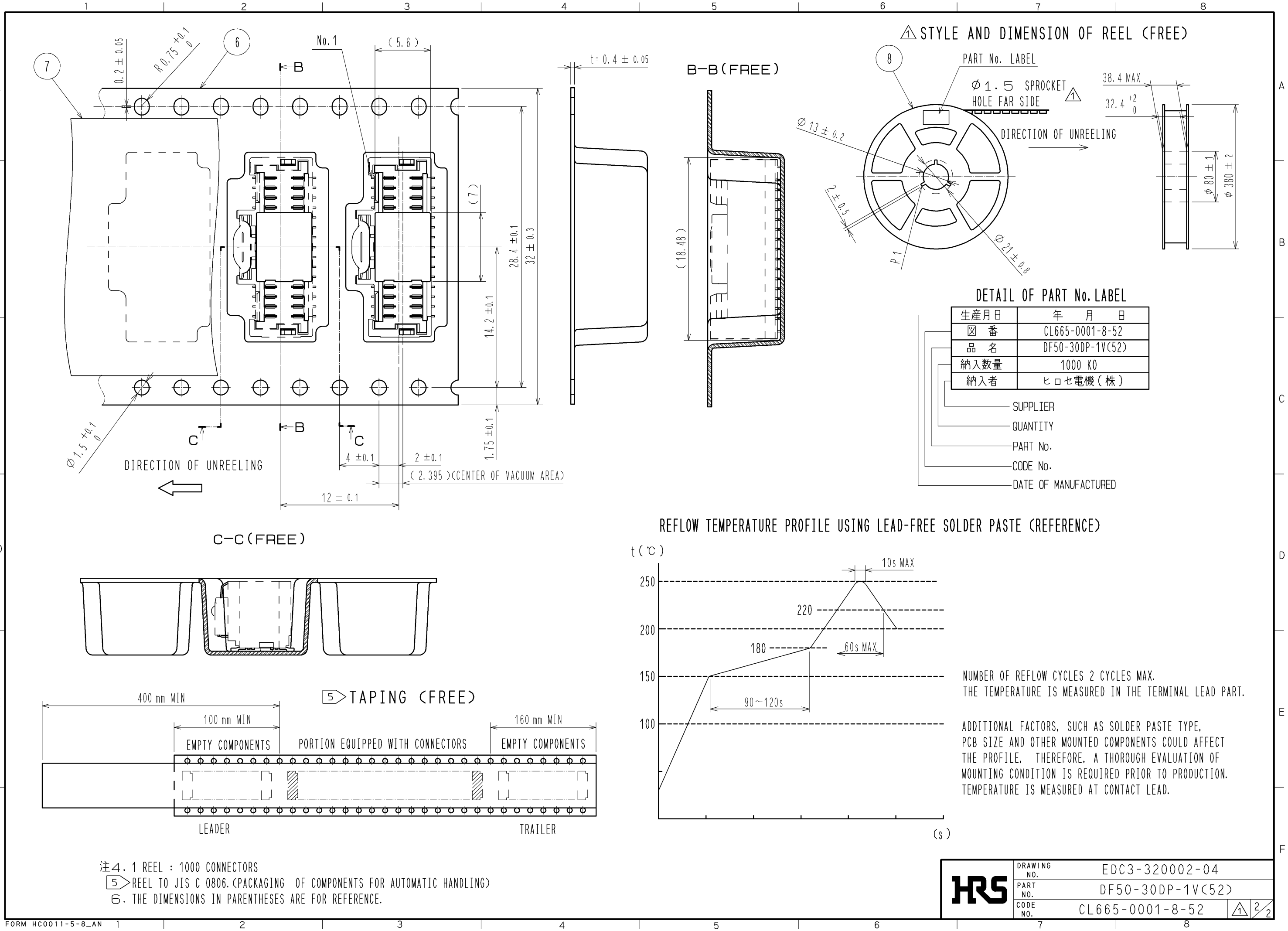
MATING FIGURE (5:1)



- NOTES 1. LEAD CO-PLANARITY SHALL BE 0.1mm MAX
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MONUTED TO FPC.

3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	8	PS	REEL , BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN LEAD AREA : Au PLATING 0.05μm MIN UNDER PLATING : Ni PLATING 1μm MIN	7	POLYESTER	CLEAR
1	LCP	BLACK , UL94V-0	6	PS	CLEAR
			5	STAINLESS STEEL	—
			4	BRASS	CONTACT AREA : Sn PLATING 1μm MIN UNDER PLATING : Ni PLATING 0.5μm MIN
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS

UNITS mm		SCALE FREE	COUNT 5	DESCRIPTION OF REVISIONS DIS-H-007735	DESIGNED MI. SAKIMURA	CHECKED TS. KUMAZAWA	DATE 13. 03. 22
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : KI. AKIYAMA 11. 11. 24	DRAWING NO. EDC3-320002-04				
		CHECED : OM. MIYAMOTO 11. 11. 22	PART NO. DF50-30DP-1V(52)				
		DESIGNED : TT. OHSAKO 11. 11. 21	CODE NO. CL665-0001-8-52				
		DRAWN : TT. OHSAKO 11. 11. 21					



HRS	DRAWING NO.	EDC3-320002-04
	PART NO.	DF50-30DP-1V(52)
	CODE NO.	CL665-0001-8-52
		2/2